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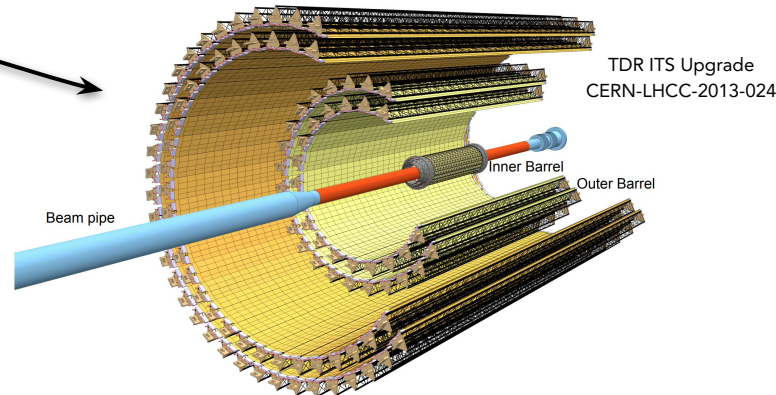
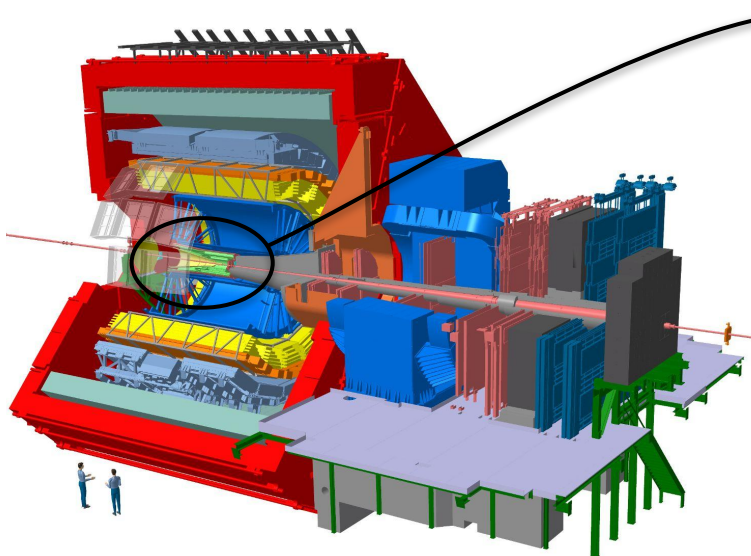
BTTB11, 17-21 April 2023

Implementation of bent pixel sensors analysis in the Corryvreckan framework

Bogdan Mihail Blidaru
on behalf of the ALICE collaboration

20.04.2023

ALICE detector



- ➡ ALICE is **the** heavy-ion physics focussed experiment at the LHC
- ➡ Main goal: study of the quark-gluon plasma in heavy-ion collisions
- ➡ Need **high resolution vertexing** and **low momentum tracking** in a **high multiplicity environment**
→ must update tracker

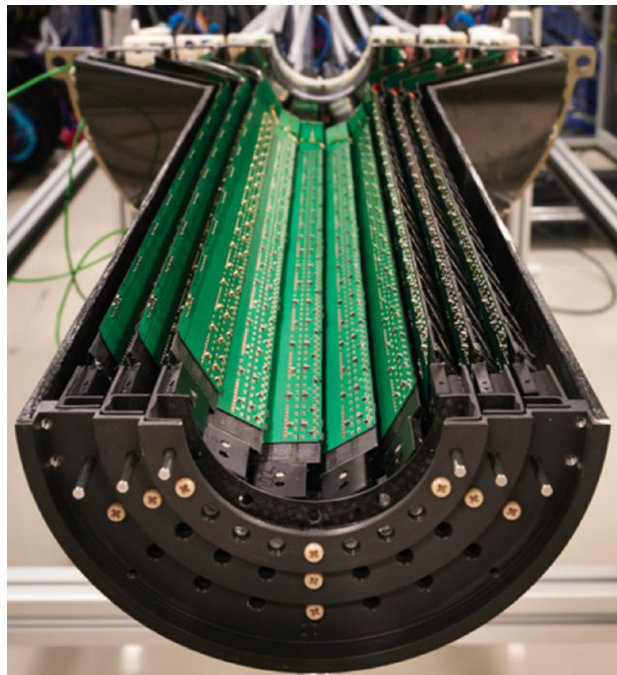
ITS2: a **full CMOS MAPS detector**

- ▶ installed during LHC Long Shutdown 2 (2021)
- ▶ 10 m² active silicon area, 12.5 Gpx
- ▶ 7 layers of **ALPIDE** sensors (3 inner + 4 outer)
- ▶ low material budget: **0.36% X₀/layer** (innermost layer)
- ▶ sensors with high detection efficiency: **≫ 99%**
- ▶ good intrinsic position resolution: **~5 μm**

ALICE - The Inner Tracking System

ITS2 inner barrel (3 layers)

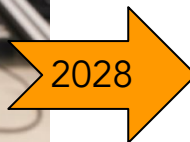
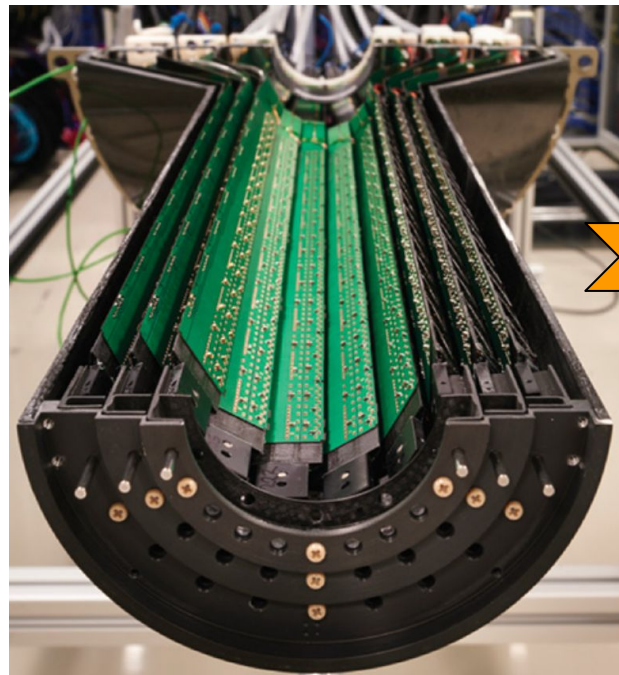
▶ 9 ALPIDE sensors / layer



ALICE - The Inner Tracking System upgrade(s)

ITS2 inner barrel (3 layers)

- ▶ 9 ALPIDE sensors / layer



ITS3

- ▶ 0.36% → 0.05% X0/layer (Si-only)



First prototype integration with dummy silicon

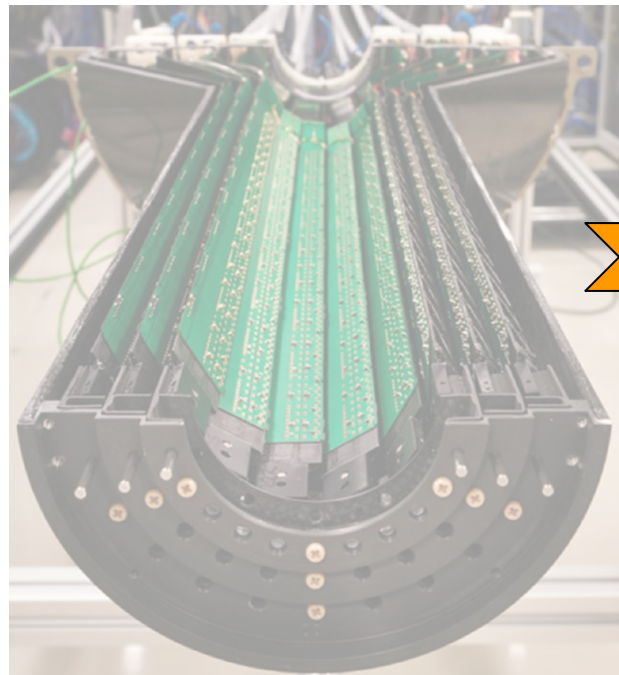
ITS3 upgrade

- ➡ LHC LS3 (2026-2028)
- ▶ replaces the 3 inner layers of the ITS2
- ▶ ultra light, wafer scale, curved sensors in 65nm

ALICE - The Inner Tracking System upgrade(s)

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2028

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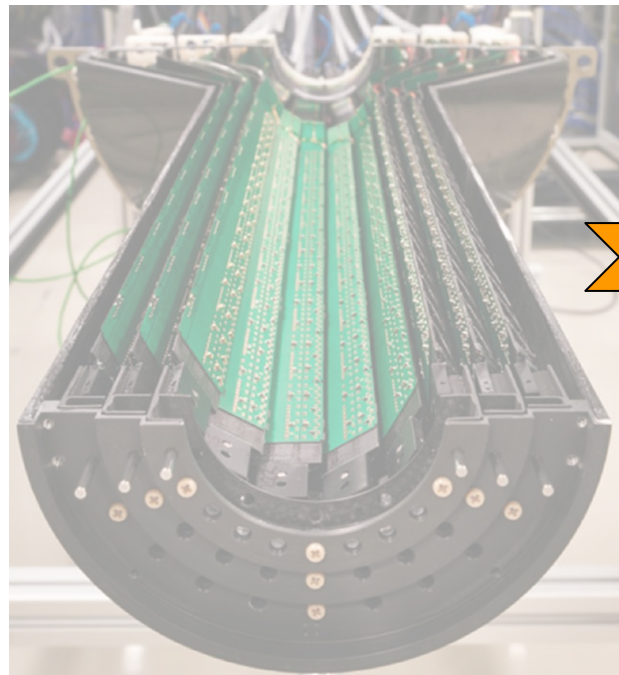
Selected R&D topics

- ▶ 65 nm testing & qualification
 - G. Alocco** ➡ talk on Thu
- ▶ wafer scale sensors
- ▶ bending of sensors

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2028

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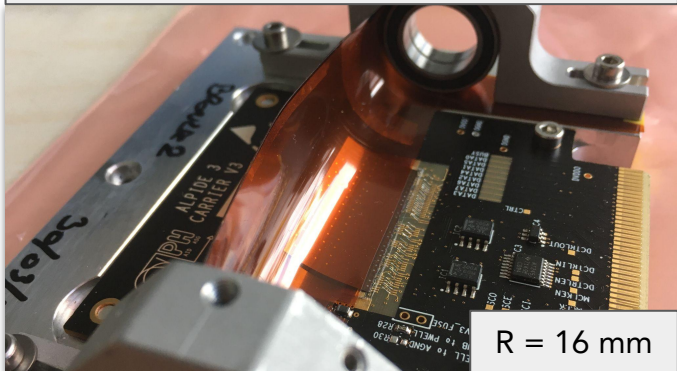
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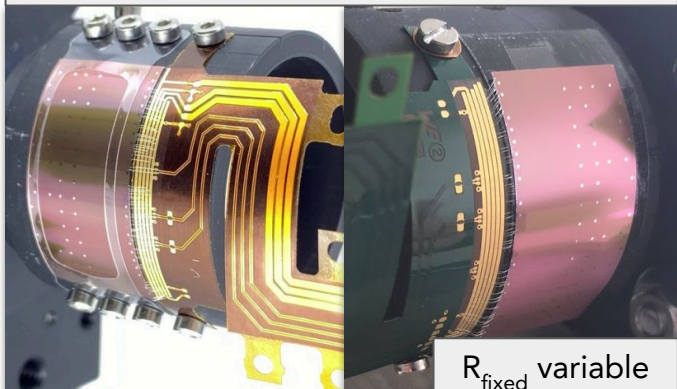
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Along the short edge, compressed circuitry



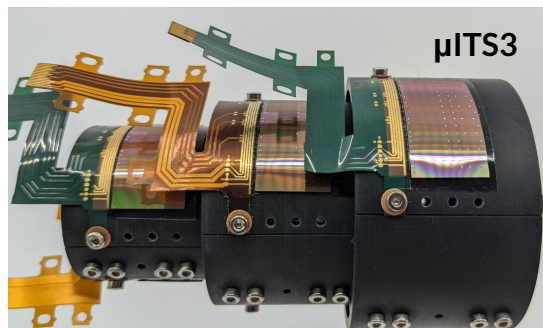
Along the long edge, stretched circuitry



Bending of ALPIDE sensors

- ➡ Functional chips bent routinely
- ➡ Electrical operation consistent (wrt flat state)
 - ▶ threshold, noise, dead pixels **unaffected**
- ➡ Setups that mimic the **radii** of the **future ITS3** (18, 24, 30 mm)
 - ▶ proven to function effectively
 - ▶ efficiency, position resolution, stability unchanged

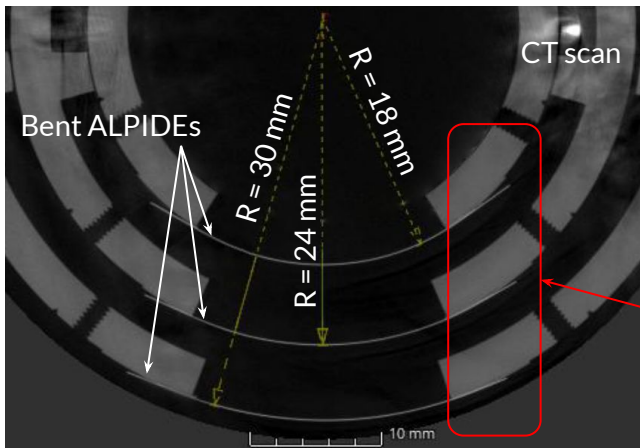
Bent MAPS working well! Performance unchanged!



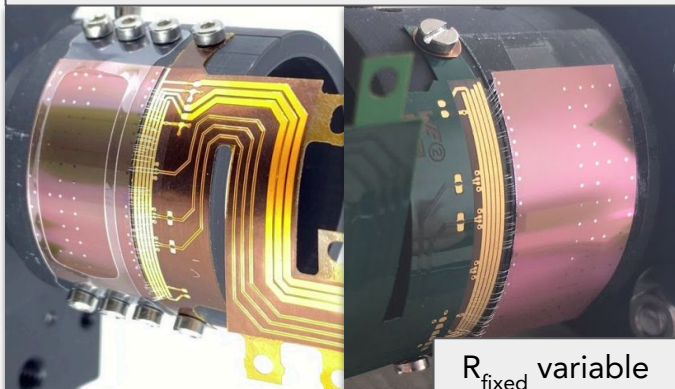
opening in the jig behind the sensor for beam tests (no material)

More details:
[10.1016/j.nima.2021.166280](https://doi.org/10.1016/j.nima.2021.166280)

Radius control



Along the long edge, stretched circuitry



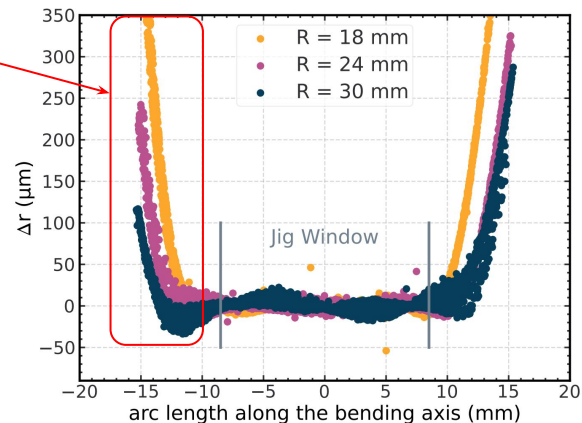
Issues observed with bending

- ➡ with first prototype, sagging (Si relaxation) was observed
 - ▶ $R_{\text{initial}} = 16\text{ mm} \rightarrow R_{\text{data}} = 22\text{ mm} \rightarrow R_{\text{final}} = 26\text{ mm}$
- ➡ consequent versions built on 3D-printed jigs
 - ▶ v1: sensor glued with tape \rightarrow can detach
 - ▶ v2: kapton sleeve keeps the sensor on the jig

Radius control

- ➡ CT and 3D profilometer scans of sensors to assess possible deviations
 - ➡ Good radius control
 - ▶ inside the jig window
- at most $30\text{ }\mu\text{m}$ deviation from R_{fixed}

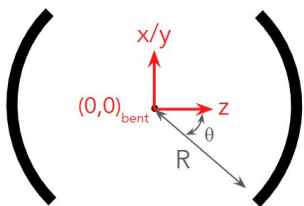
3D profilometer scan



Bent sensors in code

- ➡ Corryvreckan framework used for testbeam data analysis
- ➡ New class **BentPixelDetector** defined
 - ▶ new coordinate system: **cartesian-bent**
 - ▶ possibility to bend along rows or columns
 - ▶ **Local** to **Global** and **Global** to **Local** transformations redefined to account for bending
 - ▶ fixed **radius** of a perfect cylinder
 - ▶ rotation of sensor around the center
 - ▶ **radius** sign controls the orientation wrt beam axis

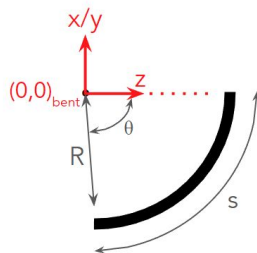
Bending along rows/columns



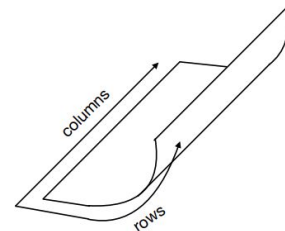
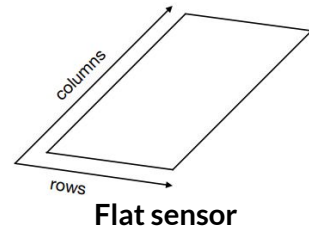
Positive R

Negative R

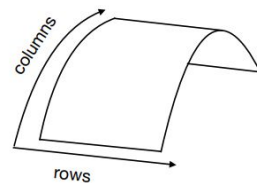
Rotated sensor (by $\theta/2$)



The Maelstrom for
Your Test Beam Data

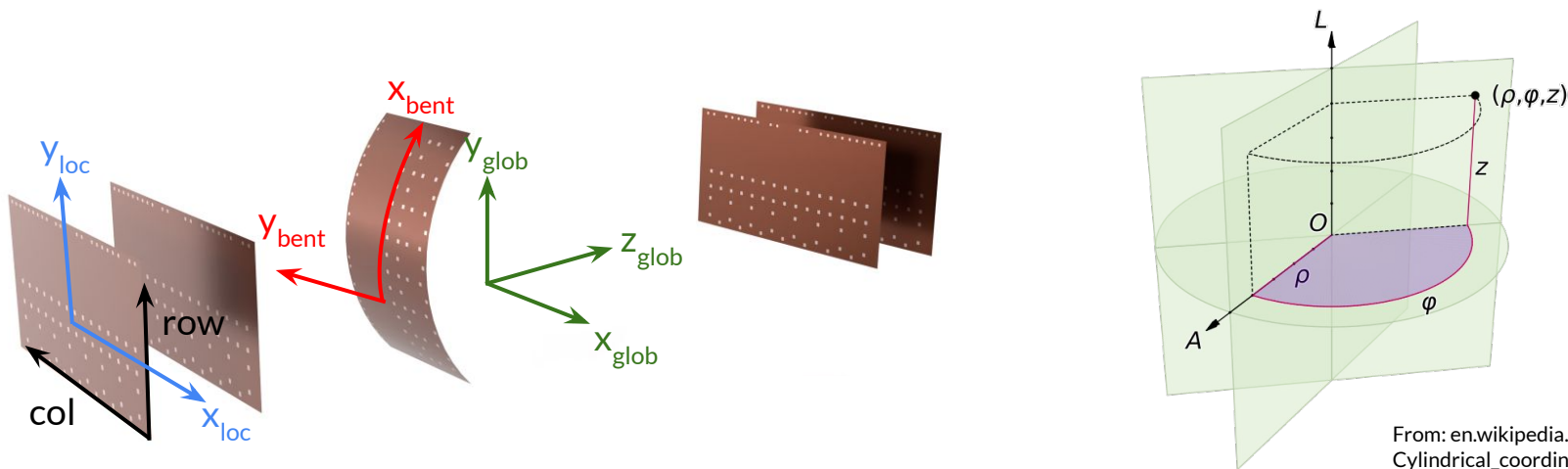


Bent along the rows



Bent along the columns

Coordinate system changes

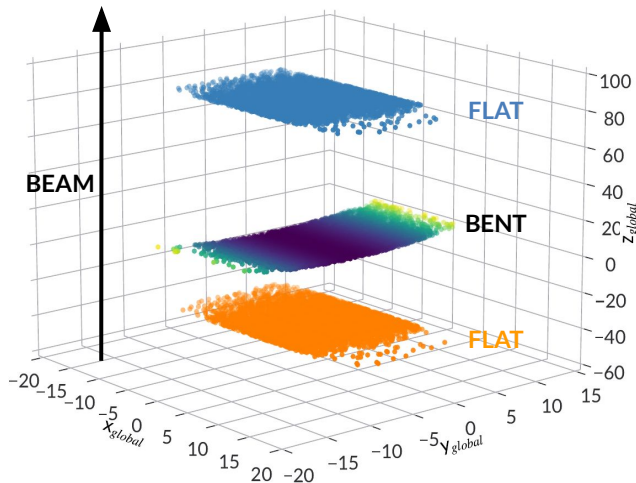


From: en.wikipedia.org/wiki/Cylindrical_coordinate_system

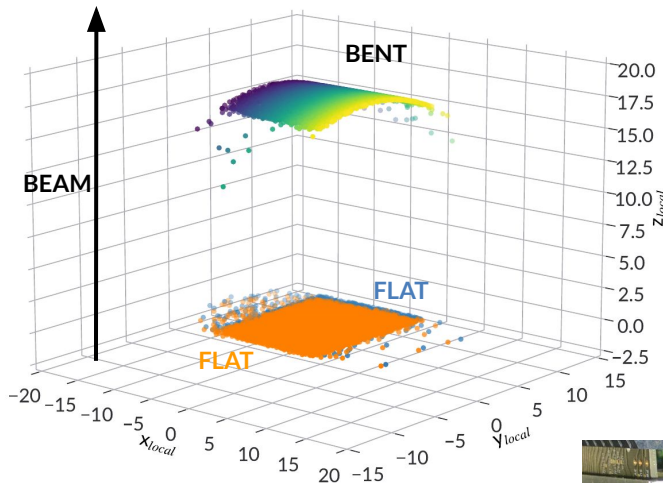
- ➡ Local position defined as a ROOT `::Math::RhoZPhiVector`
 - fixed radius (input from the user)
 - one direction (column/row) is bent, the other one is not sensitive to bending effects (along z in cylindrical coordinates)
 - only one bending direction is possible in the code

Local vs global coordinates

Clusters in global coordinates



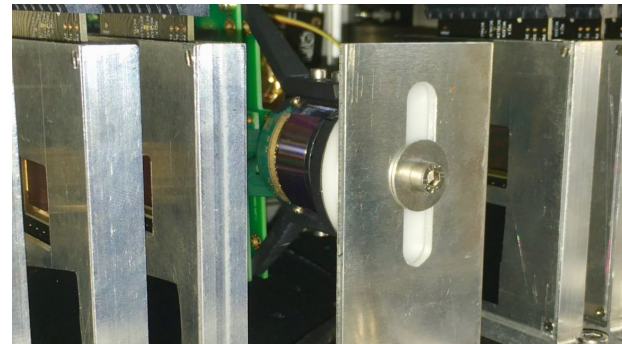
Clusters in local coordinates



```
bent_axis    = "column"  
coordinates  = "cartesian-bent"  
position     = 0mm, 0mm, 18mm  
orientation  = 0deg, 90deg, 0deg  
radius       = 18mm
```

This example

- ➡ Bent sensor with $R=18\text{ mm}$
- ➡ Facing the beam
- ➡ Rotated by 90°
(motivated by mechanics)



Local coordinate system

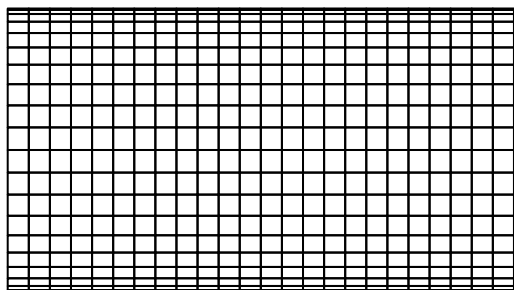
- ➡ Flat sensors fixed at $z=0$
- ➡ Bent sensor has cylinder center at $z=0$

Global coordinate system

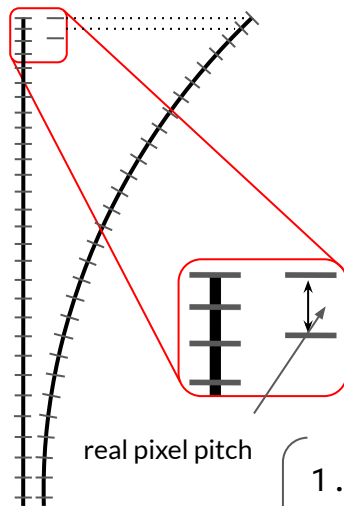
- ➡ Flat sensors have the z position from the geometry file (measured)

NB: sensors are aligned

Coordinate system changes



Pixel matrix as seen by an incoming track



➡ **Interplay of resolution** along bent direction and z direction

▶ as one grows, the other shrinks

➡ Global error matrix used for straight line fit

▶ must take z correctly into account

➡ Small uncertainty if clusters close to $z_{\text{global}}=0$, and increasing up to resolution^2 for the most bent part

$$\begin{pmatrix} \sigma_x^2 & & 0 \\ & \sigma_y^2 & \\ 0 & & \sigma_z^2 \end{pmatrix}$$

Bent sensors in code

- ➡ **Intersection** of tracks with the sensor happens at a **different z** position
- ➡ Non-zero residuals along z
- ➡ The incoming track sees “*contracted*” pixels where the sensor is bent

For 5 μm resolution of the sensors:

$$\begin{pmatrix} 1.3\text{e-}5 & 0 & 0 \\ 0 & 2.5\text{e-}5 & 0 \\ 0 & 0 & 1.1\text{e-}5 \end{pmatrix}$$

Example of global spatial resolution error matrix for a hit near the most bent part

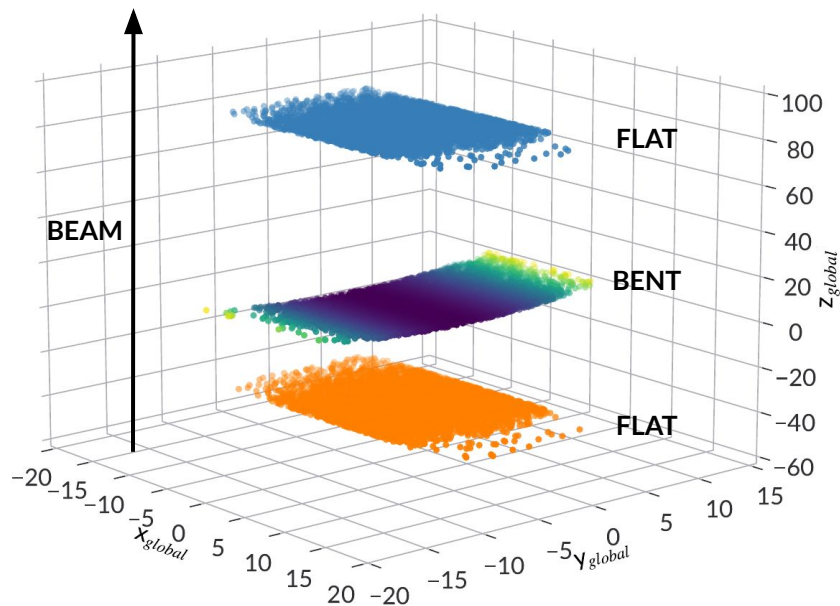
- ▶ if hit is at a large angle, the uncertainty in z is comparable with the one in x

$$\begin{pmatrix} 2.3\text{e-}5 & 0 & 0 \\ 0 & 2.5\text{e-}5 & 0 \\ 0 & 0 & 4.9\text{e-}7 \end{pmatrix}$$

Example of global spatial resolution error matrix for a somewhat central hit (flat-like sensor error matrix)

- ▶ if hit is perpendicular on surface, there is almost no uncertainty in z

All clusters

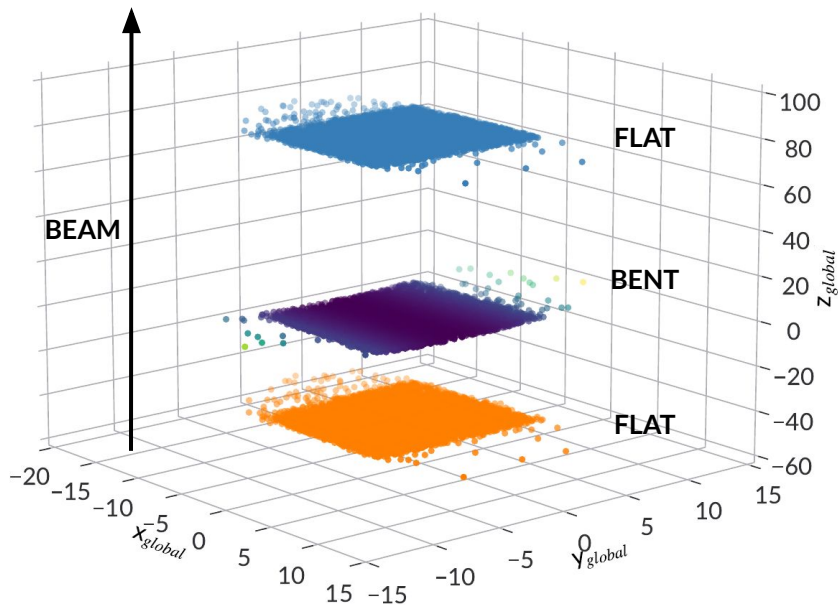


How does this actually look

- ▣ Plotting all clusters on all planes
 - trigger given by scintillator coincidence (area > sensor surface)

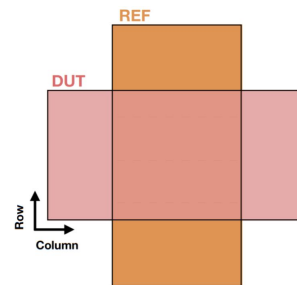
NB: sensors are aligned

One cluster per plane per event



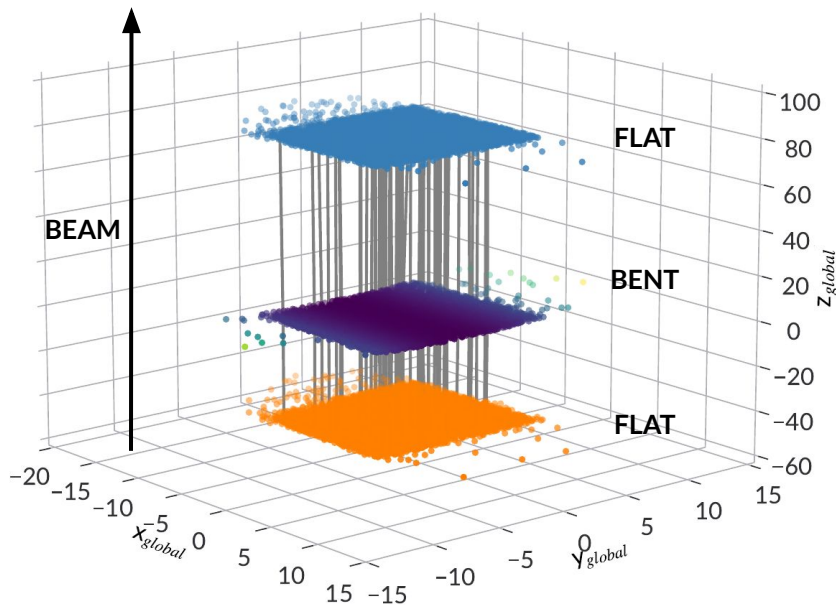
How does this actually look

- Plotting all clusters on all planes
 - trigger given by scintillator coincidence (area > sensor surface)
- Since bent sensor is 90° rotated wrt flat sensors, fiducial area is a square



NB: sensors are aligned

All cluster combinations from the different planes (only 50 shown)

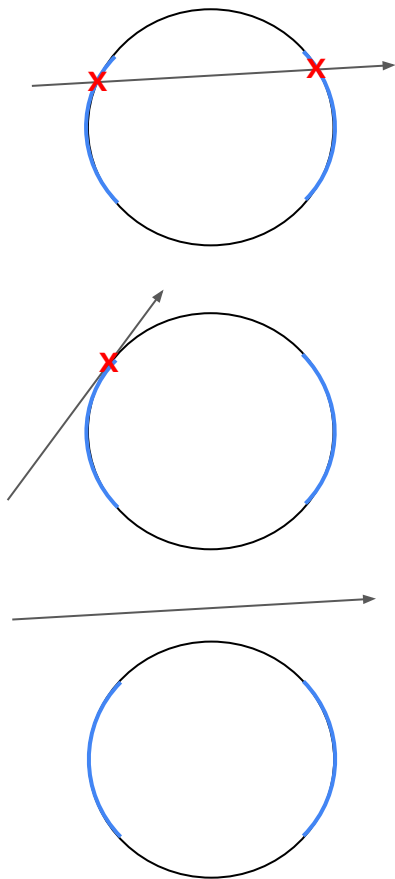


How does this actually look

- ➡ Plotting all clusters on all planes
 - ▶ trigger given by scintillator coincidence (area > sensor surface)
- ➡ Since bent sensor is 90° rotated wrt flat sensors, fiducial area is a square
- ➡ Tracking done with straight-line fit
 - line intersection with a cylinder:

NB: sensors are aligned

Intersection of tracks with sensors

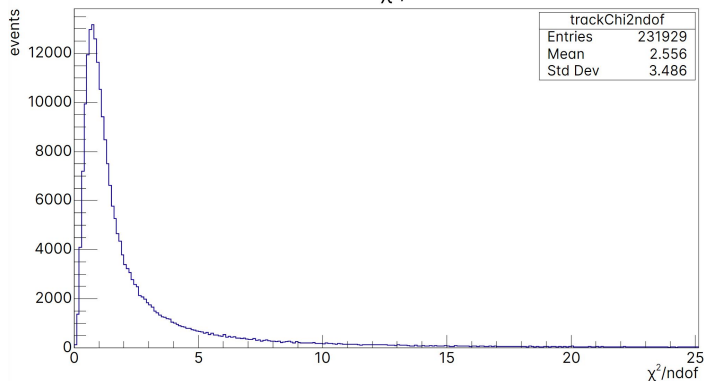


Line intersection with a cylinder

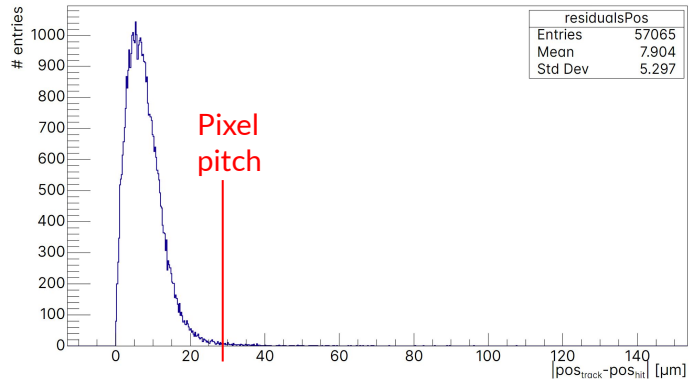
- ▣ **two** intersection points
 - select the one according to how the sensor is bent (positive R vs negative R)
 - not considering cases with grazing angle geometry
 - ▣ **one** intersection point
 - tangent on the surface
 - ▣ **no** intersection points
-
- ▣ further checks for finite sensor length
 - if sensors have limited extent and intercepts are found outside, throw an error
 - not yet implemented

A few checks

Track χ^2/ndof

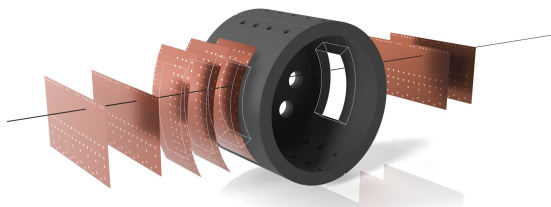


Absolute distance between track and hit in global coordinates



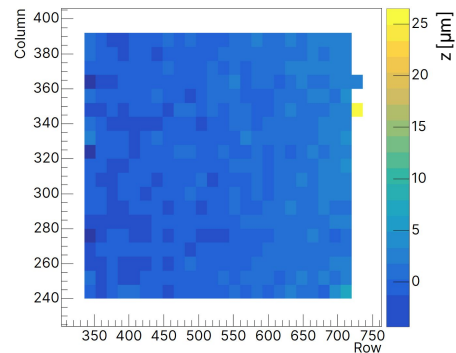
Control plots

- ➡ **Good alignment** (straight tracks)
- ➡ Distance between track intercept and hit position is **less than a pixel pitch**
- ➡ Residual mean is **uniform** and less than $10 \mu\text{m}$ over the surface
- ➡ Detachment of the sensor is remarked as increased values of the residual mean

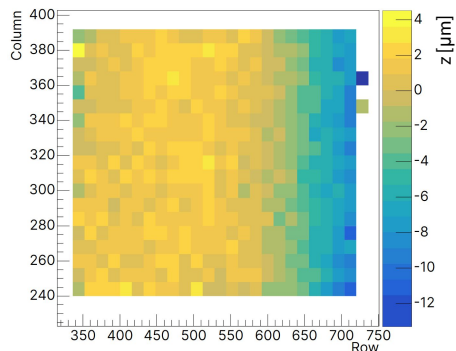


NB: 5.4 GeV e^- (DESY)

Residuals mean in the non-bent direction (y)



Residuals mean in the bent direction (x)



Until now

- ➡ Merge request submitted to Corryvreckan master
- ➡ Work ongoing (thanks Lennart!)

So far implemented

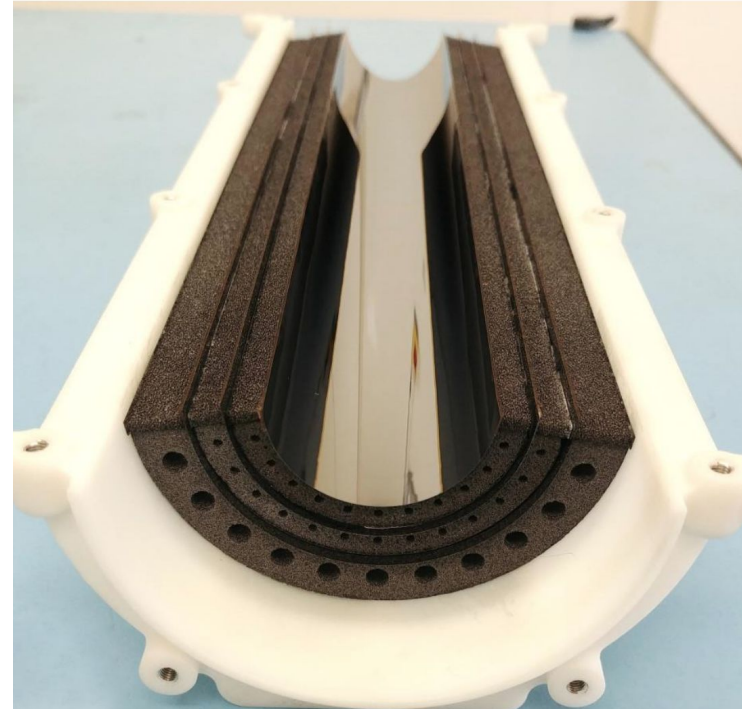
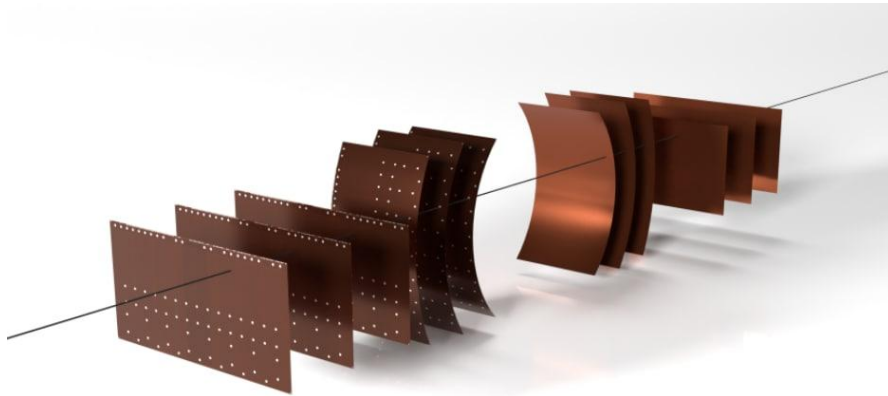
- ➡ Coordinate transformations
- ➡ Resolution in z and correct covariance matrix of spatial resolution
- ➡ Straight-line tracking and track intercept with the bent sensor

Work in progress

- ➡ General Broken Line (GBL) fit
 - calculation of the Jacobian between planes
 - assumes planar detector at position z
- ➡ Understand how degrees of freedom affect the alignment

Conclusion and outlook

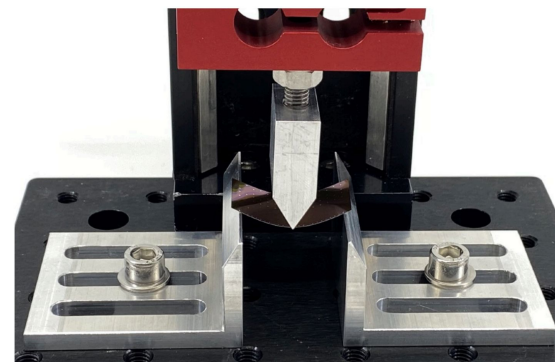
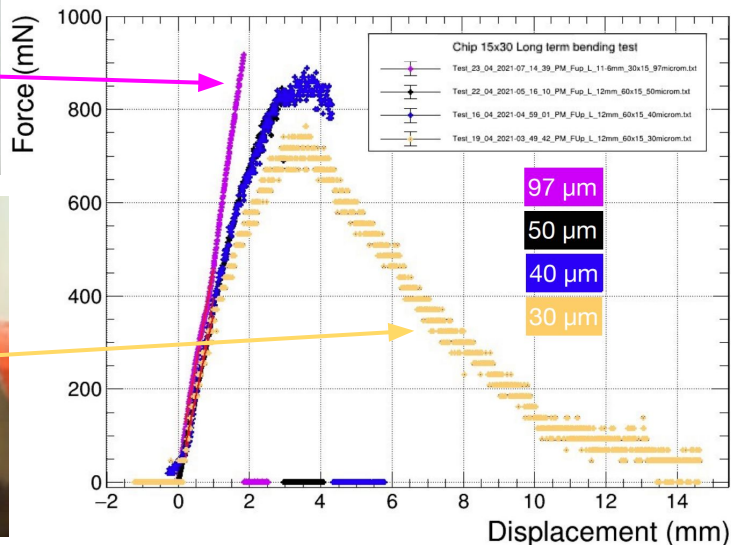
- ➡ In the near future, bent sensors will be available in Corryvreckan
- ➡ Currently working on the merge request; few more checks needed
- ➡ Work ongoing on tracking with GBL and alignment validation
- ➡ Input and suggestions are appreciated!



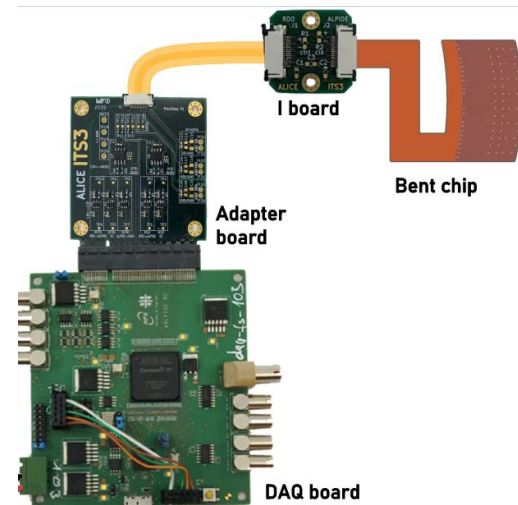
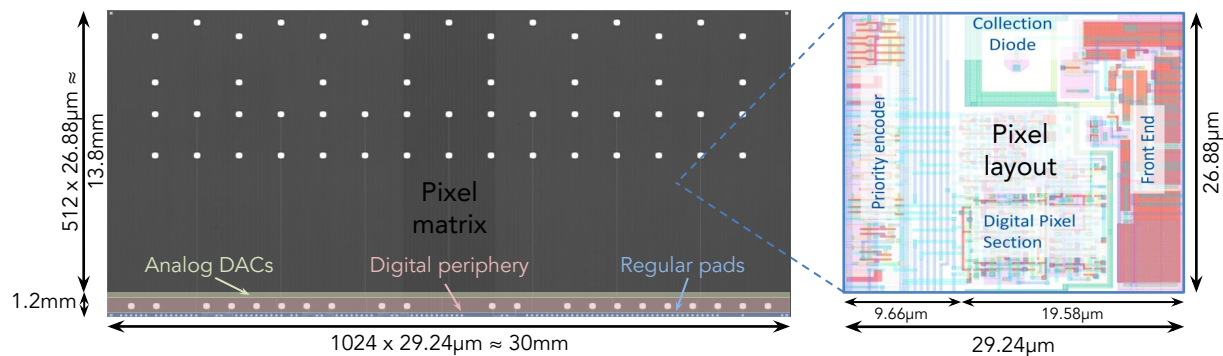
Backup



Bending tests



- ▶ ALPIDEs are in the right order of thickness: 50/100 μm vs 20-30 μm (ITS3)
- ▶ **Thinner is better**: silicon behaves like paper
- ▶ ITS3 target radii: 18, 24, 30 mm



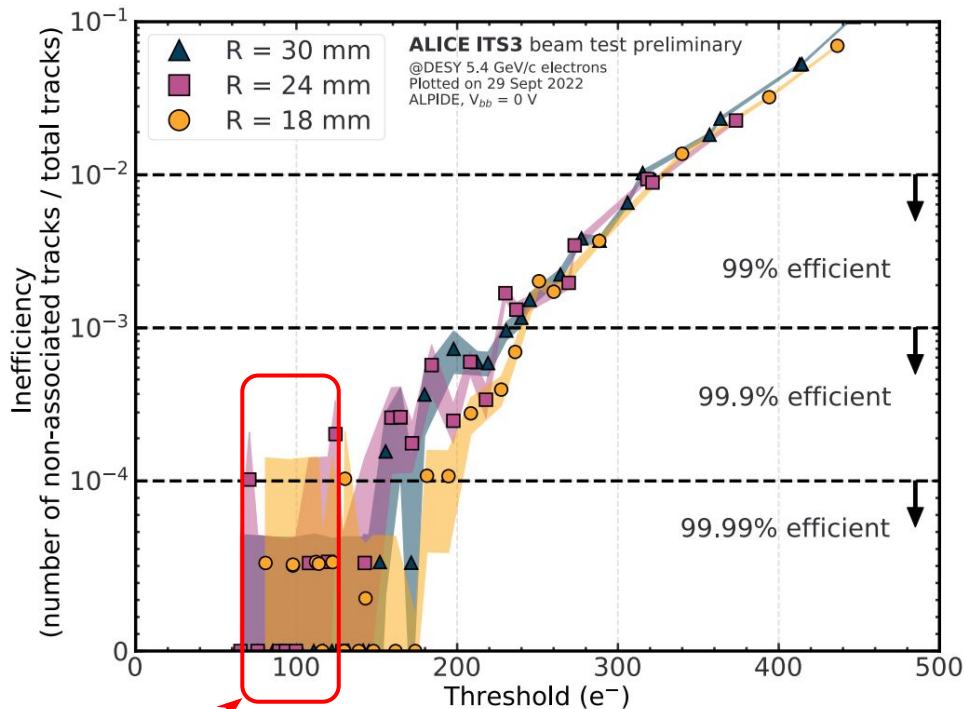
Design

- ▶ TowerJazz 180 nm CMOS Imaging Process
- ▶ High resistivity ($>1 \text{ k}\Omega\text{cm}$) p-type epitaxial layer ($25 \mu\text{m}$)
- ▶ Small NWell diode ($2 \mu\text{m}$) diameter (pixel: $29 \times 27 \mu\text{m}^2$)
→ low capacitance ($\sim \text{fF}$) → low noise
- ▶ **Reverse bias** (up to -6V) used to increase depletion

Specifications

- ▶ 0.5 Mpx sensor
- ▶ 50 / 100 μm thick (IB/OB)
- ▶ $>99.9\%$ efficient
- ▶ $\ll 10^{-6}$ fake hits/ px/ event
- ▶ $\sim 5 \mu\text{m}$ position resolution

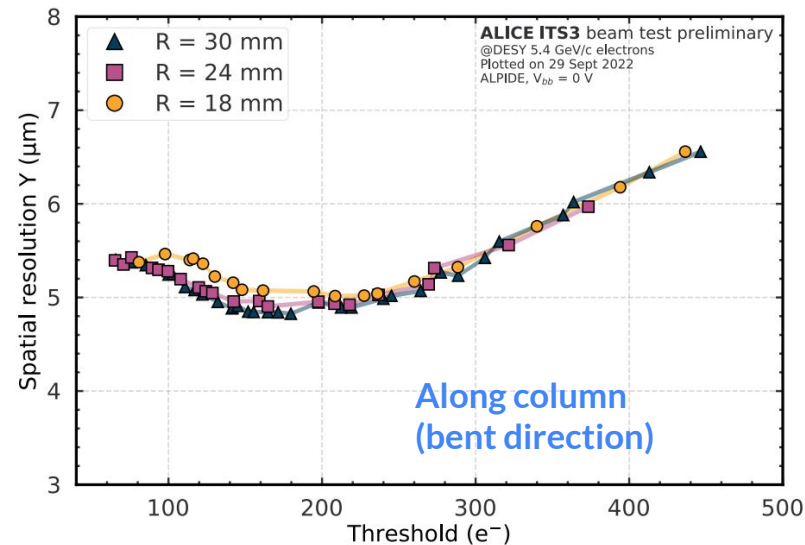
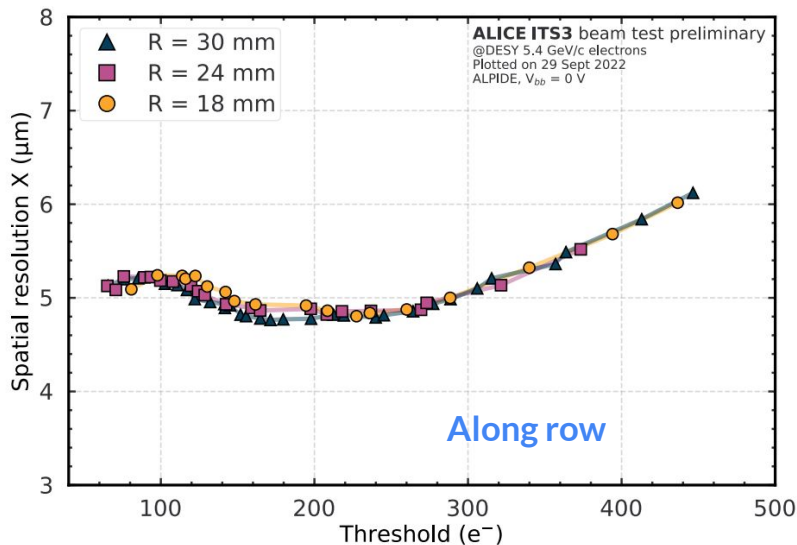
Performance of bent ALPIDEs



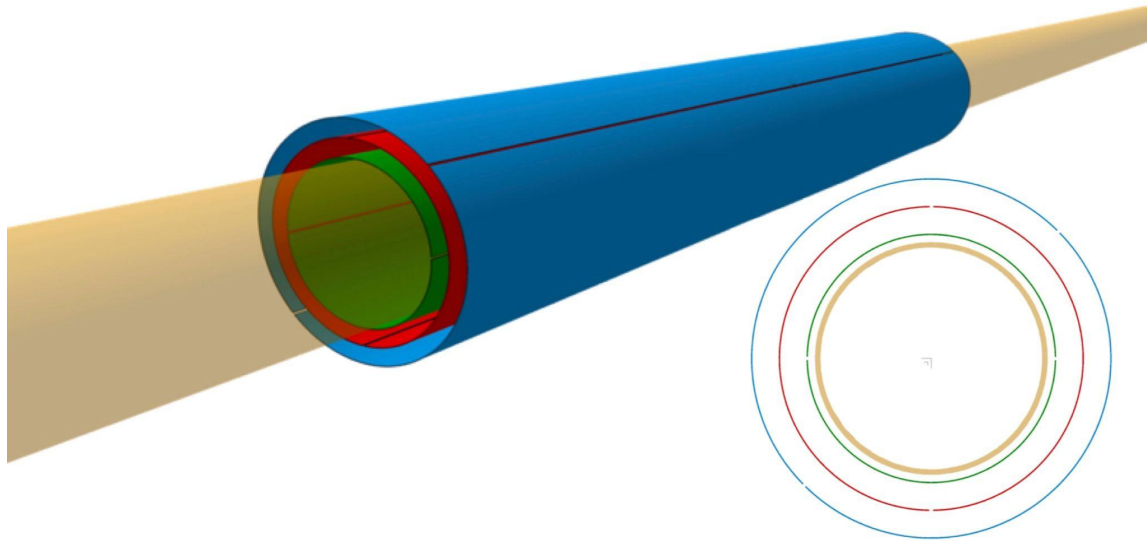
nominal operating regime

- ➡ No effects on the bending radius
- ➡ Efficiency > 99% for nominal operating regime
- ➡ Compatible with flat ALPIDE
- ➡ Consistent with published results where the other bending direction was investigated

Performance of bent ALPIDEs



- ⇒ No effects on the bending radius
- ⇒ Spatial resolution consistent with ALPIDEs in flat state (~5 μm)



➡ Ultra thin and closer to the interaction point

▶ Layer 0: 23 → 18 mm

▶ Layer thickness:

0.35 → < 0.05% X_0 /layer

(beampipe: 500 μm Be 0.14% X_0)

▶ Uniformly distributed material
(no systematic errors)

➡ Wafer scale ← stitching

➡ Layout based on air cooling

Beam pipe inner/outer radius (mm)	16.0 / 16.5		
	Layer 0	Layer 1	Layer 2
Radial distance from IP (mm)	18	24	30
Pixel sensor dimensions (mm ²)	280×56.5	280×75.5	280×94
Sensitive area length (mm)	300		
Pixel size (μm^2)	O(10×10)		

Carbon foam and cooling structures

EM1

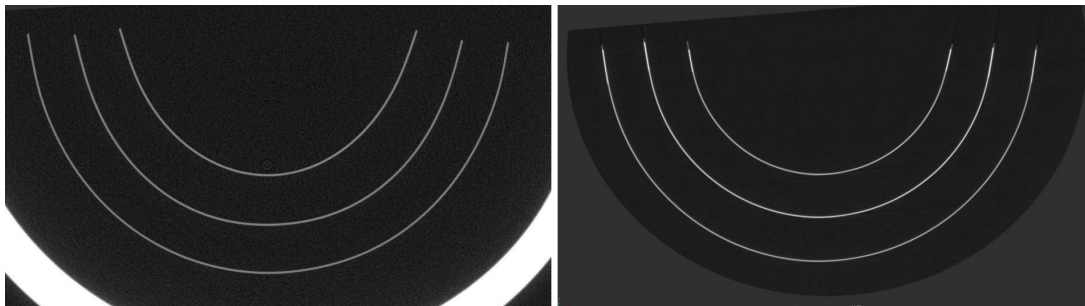
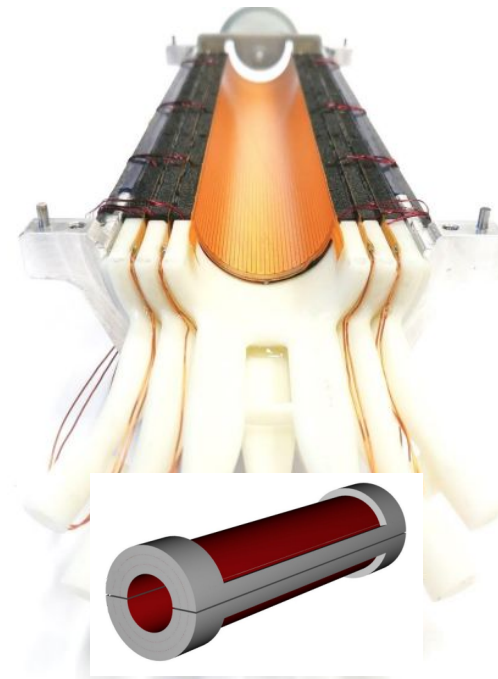


EM2



NB: EM = Engineering Model

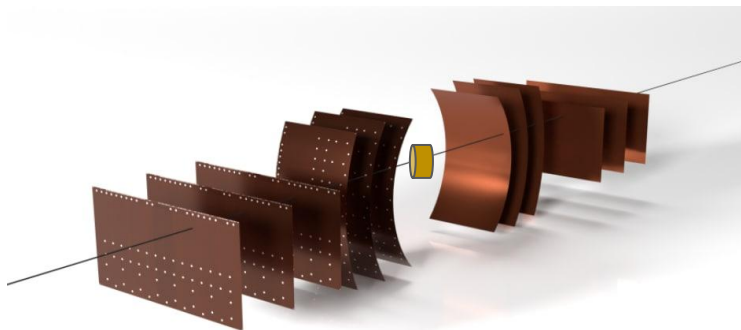
EM3



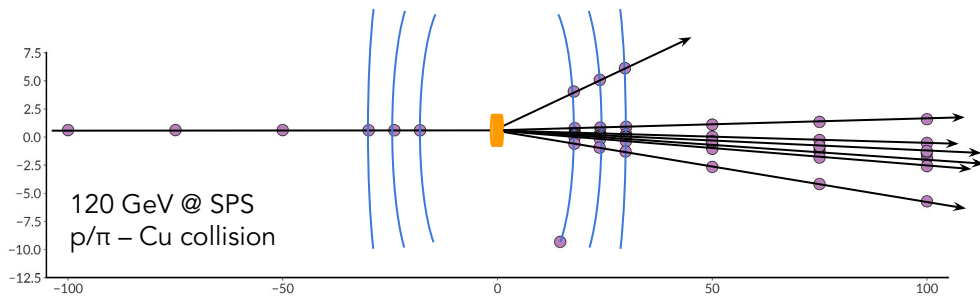
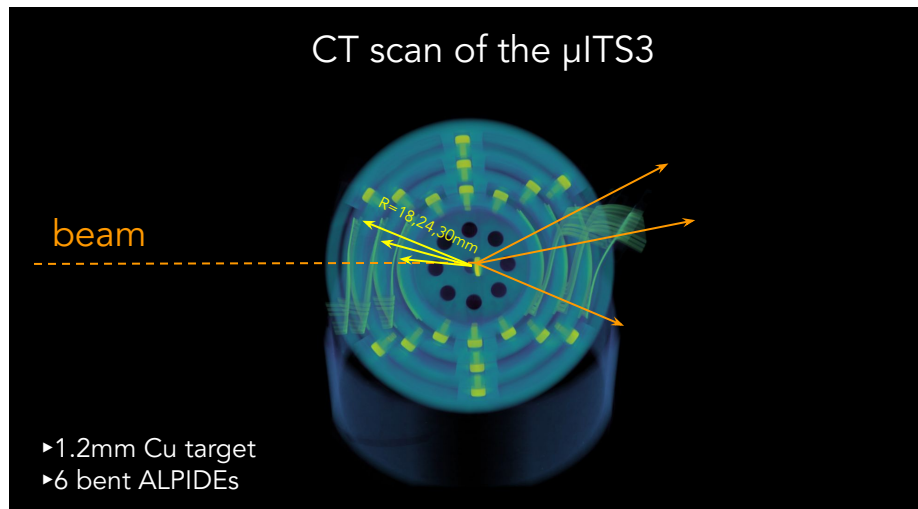
→ footprint
→ imperfect radius

→ nominal radius
→ need to add services

Exotic geometries



- ➡ 6 reference flat ALPIDE (3+3 up/downstream)
- ➡ μ ITS3: probably the most compact beam telescope (6 sensors, ITS3 radii: 18, 24, 30 mm)



- ➡ tracking with GBL (incl. multiple scattering)
- ➡ investigation of standalone tracking and DCA (distance of closest approach) measurements